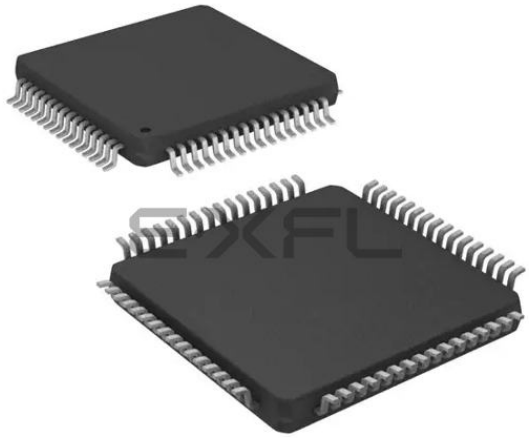

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Applications of "Embedded - Microcontrollers"

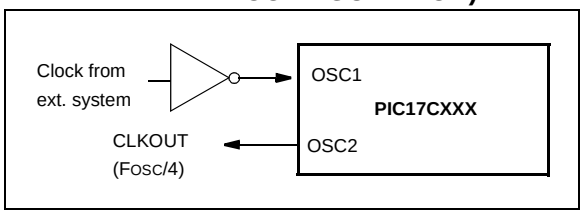
Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c752-16e-pt

NOTES:

4.1.4 EXTERNAL CLOCK OSCILLATOR

In the EC oscillator mode, the OSC1 input can be driven by CMOS drivers. In this mode, the OSC1/CLKIN pin is hi-impedance and the OSC2/CLKOUT pin is the CLKOUT output (4 TOSC).

FIGURE 4-4: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)



4.1.5 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used, or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with series resonance, or one with parallel resonance.

Figure 4-5 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometer biases the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 4-5: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

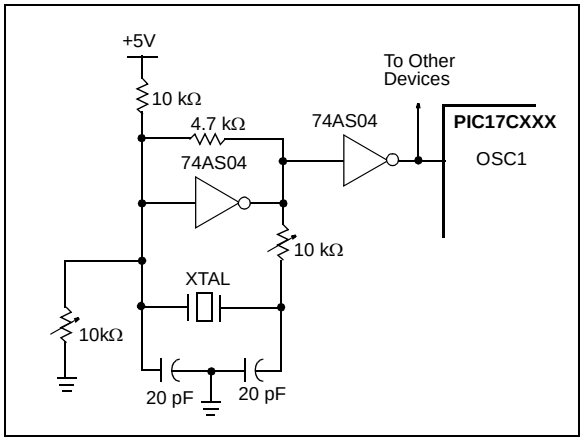
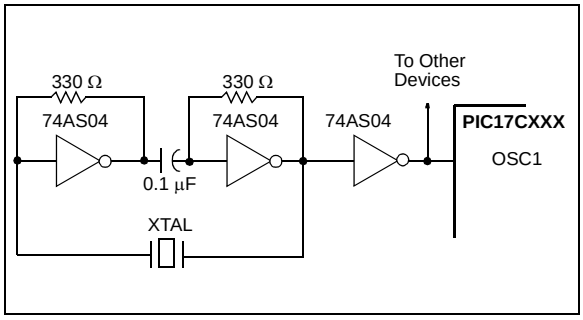


Figure 4-6 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 4-6: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



5.1 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOR)

5.1.1 POWER-ON RESET (POR)

The Power-on Reset circuit holds the device in RESET until VDD is above the trip point (in the range of 1.4V - 2.3V). The devices produce an internal RESET for both rising and falling VDD. To take advantage of the POR, just tie the MCLR/VPP pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A minimum rise time for VDD is required. See Electrical Specifications for details.

Figure 5-2 and Figure 5-3 show two possible POR circuits.

FIGURE 5-2: USING ON-CHIP POR

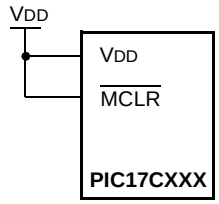
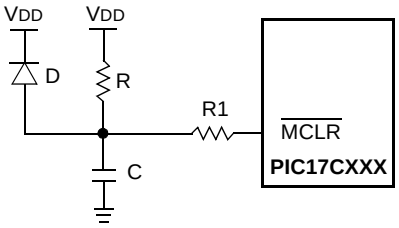


FIGURE 5-3: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: An external Power-on Reset circuit is required only if VDD power-up time is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to ensure that the voltage drop across R does not exceed 0.2V (max. leakage current spec. on the MCLR/VPP pin is 5 μA). A larger voltage drop will degrade VIH level on the MCLR/VPP pin.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

5.1.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 96 ms time-out (nominal) on power-up. This occurs from the rising edge of the internal POR signal if VDD and MCLR are tied, or after the first rising edge of MCLR (detected high). The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. In most cases, the PWRT delay allows VDD to rise to an acceptable level.

The power-up time delay will vary from chip to chip and with VDD and temperature. See DC parameters for details.

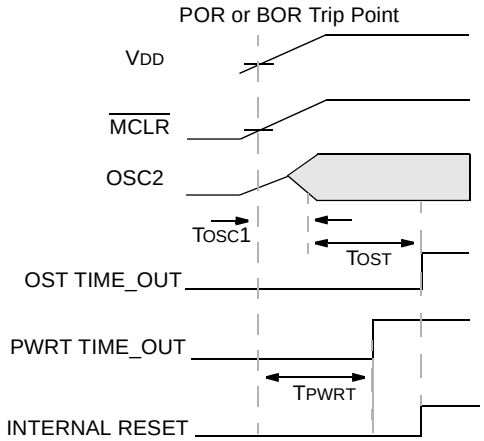
5.1.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (1024TOSC) delay whenever the PWRT is invoked, or a wake-up from SLEEP event occurs in XT or LF mode. The PWRT and OST operate in parallel.

The OST counts the oscillator pulses on the OSC1/CLKIN pin. The counter only starts incrementing after the amplitude of the signal reaches the oscillator input thresholds. This delay allows the crystal oscillator or resonator to stabilize before the device exits RESET. The length of the time-out is a function of the crystal/resonator frequency.

Figure 5-4 shows the operation of the OST circuit. In this figure, the oscillator is of such a low frequency that although enabled simultaneously, the OST does not time-out until after the Power-up Timer time-out.

FIGURE 5-4: OSCILLATOR START-UP TIME (LOW FREQUENCY)



This figure shows in greater detail the timings involved with the oscillator start-up timer. In this example, the low frequency crystal start-up time is larger than power-up time (TPWRT).

TOSC1 = time for the crystal oscillator to react to an oscillation level detectable by the Oscillator Start-up Timer (OST).

TOST = 1024TOSC.

NOTES:

13.1.2 TIMER1 AND TIMER2 IN 16-BIT MODE

To select 16-bit mode, set the T16 bit. In this mode, TMR2 and TMR1 are concatenated to form a 16-bit timer (TMR2:TMR1). The 16-bit timer increments until it matches the 16-bit period register (PR2:PR1). On the following timer clock, the timer value is reset to 0h, and the TMR1IF bit is set.

When selecting the clock source for the 16-bit timer, the TMR1CS bit controls the entire 16-bit timer and TMR2CS is a “don’t care”, however, ensure that TMR2ON is set (allows TMR2 to increment). When TMR1CS is clear, the timer increments once every instruction cycle (FOSC/4). When TMR1CS is set, the timer increments on every falling edge of the RB4/TCLK12 pin. For the 16-bit timer to increment, both TMR1ON and TMR2ON bits must be set (Table 13-2).

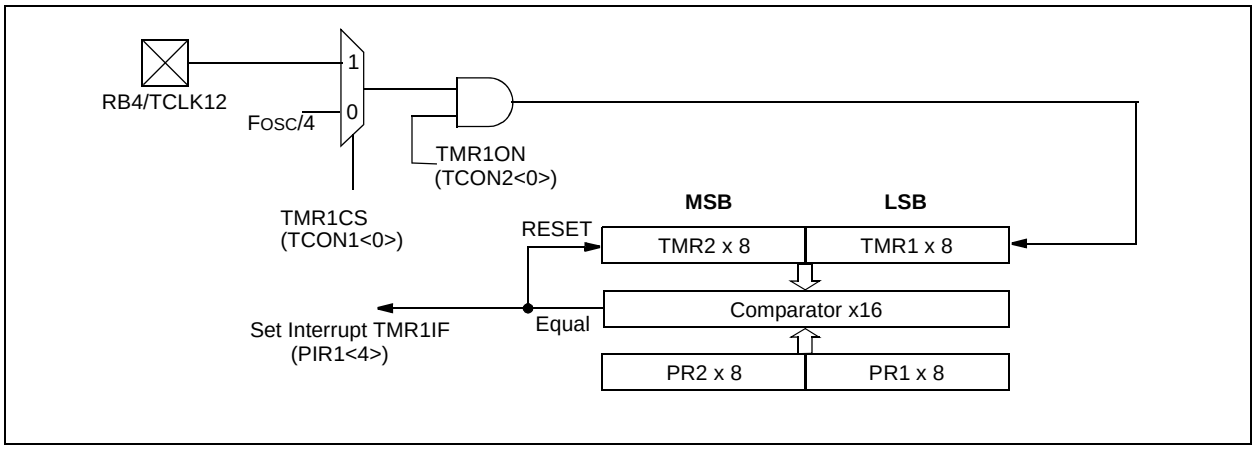
13.1.2.1 External Clock Input for TMR2:TMR1

When TMR1CS is set, the 16-bit TMR2:TMR1 increments on the falling edge of clock input TCLK12. The input on the RB4/TCLK12 pin is sampled and synchronized by the internal phase clocks twice every instruction cycle. This causes a delay from the time a falling edge appears on RB4/TCLK12 to the time TMR2:TMR1 is actually incremented. For the external clock input timing requirements, see the Electrical Specification section.

TABLE 13-2: TURNING ON 16-BIT TIMER

T16	TMR2ON	TMR1ON	Result
1	1	1	16-bit timer (TMR2:TMR1) ON
1	0	1	Only TMR1 increments
1	x	0	16-bit timer OFF
0	1	1	Timers in 8-bit mode

FIGURE 13-2: TMR2 AND TMR1 IN 16-BIT TIMER/COUNTER MODE



This mode (3 Capture, 1 Period) is selected if control bit CA1/PR3 is clear. In this mode, the Capture1 register, consisting of high byte (PR3H/CA1H) and low byte (PR3L/CA1L), is configured as the period control register for TMR3. Capture1 is disabled in this mode and the corresponding interrupt bit, CA1IF, is never set. TMR3 increments until it equals the value in the period register and then resets to 0000h on the next timer clock.

All other Captures are active in this mode.

13.2.1.1 Capture Operation

The CAxED1 and CAxED0 bits determine the event on which capture will occur. The possible events are:

- Capture on every falling edge
- Capture on every rising edge
- Capture every 4th rising edge
- Capture every 16th rising edge

When a capture takes place, an interrupt flag is latched into the CAxIF bit. This interrupt can be enabled by setting the corresponding mask bit CAxIE. The Peripheral Interrupt Enable bit (PEIE) must be set and the Global Interrupt Disable bit (GLINTD) must be cleared for the interrupt to be acknowledged. The CAxIF interrupt flag bit is cleared in software.

When the capture prescale select is changed, the prescaler is not reset and an event may be generated. Therefore, the first capture after such a change will be ambiguous. However, it sets the time-base for the next capture. The prescaler is reset upon chip RESET.

The capture pin, CAPx, is a multiplexed pin. When used as a port pin, the capture is not disabled. However, the user can simply disable the Capture interrupt by clearing CAxIE. If the CAPx pin is used as an output pin, the user can activate a capture by writing to the port pin. This may be useful during development phase to emulate a capture interrupt.

The input on the capture pin CAPx is synchronized internally to internal phase clocks. This imposes certain restrictions on the input waveform (see the Electrical Specification section for timing).

The capture overflow status flag bit is double buffered. The master bit is set if one captured word is already residing in the Capture register (CAxH:CAxL) and another “event” has occurred on the CAPx pin. The new event will not transfer the TMR3 value to the capture register, protecting the previous unread capture value. When the user reads both the high and the low bytes (in any order) of the Capture register, the master overflow bit is transferred to the slave overflow bit (CAxOVF) and then the master bit is reset. The user can then read TCONx to determine the value of CAxOVF.

The recommended sequence to read capture registers and capture overflow flag bits is shown in Example 13-1.

14.3 USART Synchronous Master Mode

In Master Synchronous mode, the data is transmitted in a half-duplex manner; i.e., transmission and reception do not occur at the same time: when transmitting data, the reception is inhibited and vice versa. The synchronous mode is entered by setting the SYNC (TXSTA<4>) bit. In addition, the SPEN (RCSTA<7>) bit is set in order to configure the I/O pins to CK (clock) and DT (data) lines, respectively. The Master mode indicates that the processor transmits the master clock on the CK line. The Master mode is entered by setting the CSRC (TXSTA<7>) bit.

14.3.1 USART SYNCHRONOUS MASTER TRANSMISSION

The USART transmitter block diagram is shown in Figure 14-1. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer TXREG. TXREG is loaded with data in software. The TSR is not loaded until the last bit has been transmitted from the previous load. As soon as the last bit is transmitted, the TSR is loaded with new data from TXREG (if available). Once TXREG transfers the data to the TSR (occurs in one T_{CY} at the end of the current BRG cycle), TXREG is empty and the TXIF bit is set. This interrupt can be enabled/disabled by setting/clearing the TXIE bit. TXIF will be set regardless of the state of bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into TXREG. While TXIF indicates the status of TXREG, TRMT (TXSTA<1>) shows the status of the TSR. TRMT is a read only bit which is set when the TSR is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR is empty. The TSR is not mapped in data memory, so it is not available to the user.

Transmission is enabled by setting the TXEN (TXSTA<5>) bit. The actual transmission will not occur until TXREG has been loaded with data. The first data bit will be shifted out on the next available rising edge of the clock on the TX/CK pin. Data out is stable around the falling edge of the synchronous clock (Figure 14-9). The transmission can also be started by first loading TXREG and then setting TXEN. This is advantageous when slow baud rates are selected, since BRG is kept in RESET when the TXEN, CREN, and SREN bits are clear. Setting the TXEN bit will start the BRG, creating a shift clock immediately. Normally when transmission is first started, the TSR is empty, so a transfer to TXREG will result in an immediate transfer to the TSR, resulting in an empty TXREG. Back-to-back transfers are possible.

Clearing TXEN during a transmission will cause the transmission to be aborted and will reset the transmitter. The RX/DT and TX/CK pins will revert to hi-impedance. If either CREN or SREN are set during a transmission, the transmission is aborted and the RX/DT pin reverts to a hi-impedance state (for a reception). The TX/CK pin will remain an output if the CSRC bit is set (internal clock). The transmitter logic is not reset, although it is disconnected from the pins. In order to reset the transmitter, the user has to clear the TXEN bit. If the SREN bit is set (to interrupt an ongoing transmission and receive a single word), then after the single word is received, SREN will be cleared and the serial port will revert back to transmitting, since the TXEN bit is still set. The DT line will immediately switch from hi-impedance Receive mode to transmit and start driving. To avoid this, TXEN should be cleared.

In order to select 9-bit transmission, the TX9 (TXSTA<6>) bit should be set and the ninth bit should be written to TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to TXREG. This is because a data write to TXREG can result in an immediate transfer of the data to the TSR (if the TSR is empty). If the TSR was empty and TXREG was written before writing the “new” TX9D, the “present” value of TX9D is loaded.

Steps to follow when setting up a Synchronous Master Transmission:

1. Initialize the SPBRG register for the appropriate baud rate (see Baud Rate Generator Section for details).
2. Enable the synchronous master serial port by setting the SYNC, SPEN, and CSRC bits.
3. Ensure that the CREN and SREN bits are clear (these bits override transmission when set).
4. If interrupts are desired, then set the TXIE bit (the GLINTD bit must be clear and the PEIE bit must be set).
5. If 9-bit transmission is desired, then set the TX9 bit.
6. If 9-bit transmission is selected, the ninth bit should be loaded in TX9D.
7. Start transmission by loading data to the TXREG register.
8. Enable the transmission by setting TXEN.

Writing the transmit data to the TXREG, then enabling the transmit (setting TXEN), allows transmission to start sooner than doing these two events in the reverse order.

Note:	To terminate a transmission, either clear the SPEN bit, or the TXEN bit. This will reset the transmit logic, so that it will be in the proper state when transmit is re-enabled.

15.3 Connection Considerations for I²C Bus

For standard mode I²C bus devices, the values of resistors R_p R_s in Figure 15-42 depends on the following parameters:

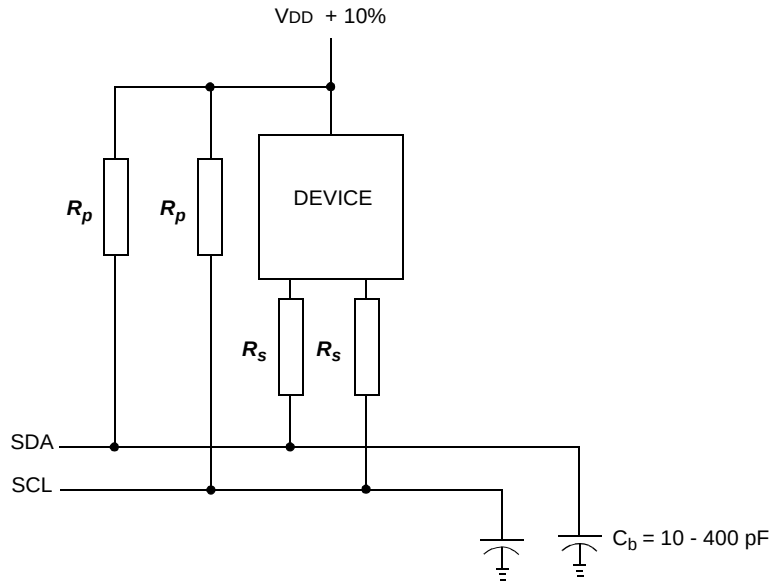
- Supply voltage
- Bus capacitance
- Number of connected devices (input current + leakage current)

The supply voltage limits the minimum value of resistor R_p due to the specified minimum sink current of 3 mA at VOL max = 0.4V for the specified output stages. For example, with a supply voltage of VDD = 5V ±10% and VOL max = 0.4V at 3 mA, R_p min = (5.5-0.4)/0.003 = 1.7 kΩ. VDD as a function of R_p is shown in Figure 15-42. The desired noise margin of 0.1 VDD for the low level, limits the maximum value of R_s. Series resistors are optional and used to improve ESD susceptibility.

The bus capacitance is the total capacitance of wire, connections and pins. This capacitance limits the maximum value of R_p due to the specified rise time (Figure 15-42).

The SMP bit is the slew rate control enabled bit. This bit is in the SSPSTAT register and controls the slew rate of the I/O pins when in I²C mode (master or slave).

FIGURE 15-42: SAMPLE DEVICE CONFIGURATION FOR I²C BUS



Note: I²C devices with input levels related to VDD must have one common supply line to which the pull-up resistor is also connected.

16.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The analog-to-digital (A/D) converter module has twelve analog inputs for the PIC17C75X devices and sixteen for the PIC17C76X devices.

The analog input charges a sample and hold capacitor. The output of the sample and hold capacitor is the input into the converter. The converter then generates a digital result of this analog level via successive approximation. This A/D conversion of the analog input signal, results in a corresponding 10-bit digital number.

The analog reference voltages (positive and negative supply) are software selectable to either the device's supply voltages (AVDD, AVss), or the voltage level on the RG3/AN0/VREF+ and RG2/AN1/VREF- pins.

The A/D converter has a unique feature of being able to operate while the device is in SLEEP mode. To operate in SLEEP, the A/D clock must be derived from the A/D's internal RC oscillator.

The A/D module has four registers. These registers are:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register0 (ADCON0)
- A/D Control Register1 (ADCON1)

The ADCON0 register, shown in Register 16-1, controls the operation of the A/D module. The ADCON1 register, shown in Register 16-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RG3 and RG2 can also be the voltage references), or as digital I/O.

REGISTER 16-1: ADCON0 REGISTER (ADDRESS: 14h, BANK 5)

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0	R/W-0
CHS3	CHS2	CHS1	CHS0	—	GO/$\overline{\text{DONE}}$	—	$\overline{\text{ADON}}$
bit 7							bit 0

bit 7-4 **CHS3:CHS0**: Analog Channel Select bits
0000 = channel 0, (AN0)
0001 = channel 1, (AN1)
0010 = channel 2, (AN2)
0011 = channel 3, (AN3)
0100 = channel 4, (AN4)
0101 = channel 5, (AN5)
0110 = channel 6, (AN6)
0111 = channel 7, (AN7)
1000 = channel 8, (AN8)
1001 = channel 9, (AN9)
1010 = channel 10, (AN10)
1011 = channel 11, (AN11)
1100 = channel 12, (AN12) (PIC17C76X only)
1101 = channel 13, (AN13) (PIC17C76X only)
1110 = channel 14, (AN14) (PIC17C76X only)
1111 = channel 15, (AN15) (PIC17C76X only)
11xx = **RESERVED**, do not select (PIC17C75X only)

bit 3 **Unimplemented**: Read as '0'

bit 2 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit

If ADON = 1:
1 = A/D conversion in progress (setting this bit starts the A/D conversion, which is automatically cleared by hardware when the A/D conversion is complete)
0 = A/D conversion not in progress

bit 1 **Unimplemented**: Read as '0'

bit 0 **ADON**: A/D On bit
1 = A/D converter module is operating
0 = A/D converter module is shut-off and consumes no operating current

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

16.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires a minimum 12TAD per 10-bit conversion. The source of the A/D conversion clock is software selected. The four possible options for TAD are:

- 8TOSC
- 32TOSC
- 64TOSC
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 μs.

Table 16-1 and Table 16-2 show the resultant TAD times derived from the device operating frequencies and the A/D clock source selected. These times are for standard voltage range devices.

TABLE 16-1: TAD vs. DEVICE OPERATING FREQUENCIES (STANDARD DEVICES (C))

AD Clock Source (TAD)		Max FOSC (MHz)
Operation	ADCS1:ADCS0	
8TOSC	00	5
32TOSC	01	20
64TOSC	10	33
RC	11	—

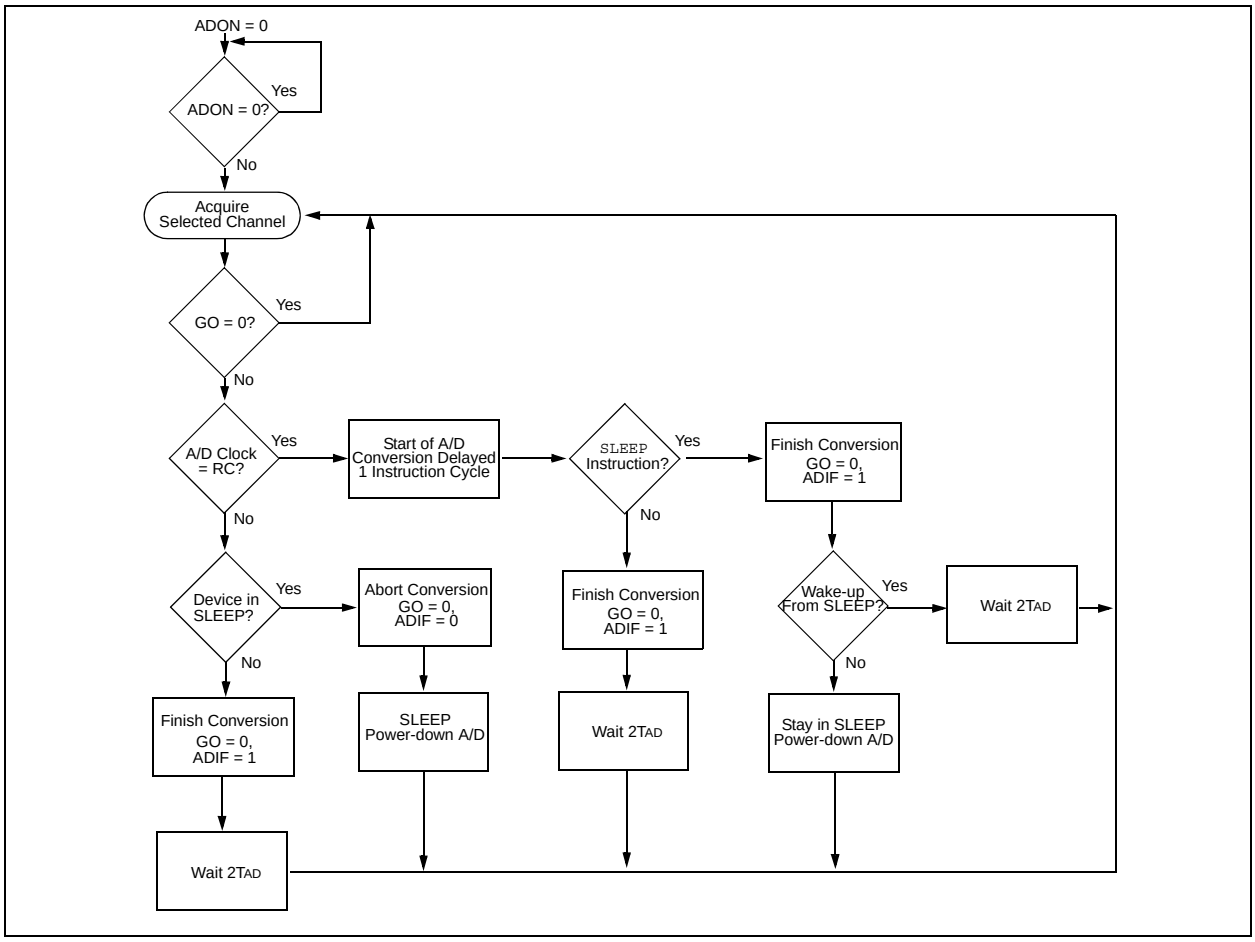
Note: When the device frequency is greater than 1 MHz, the RC A/D conversion clock source is only recommended for SLEEP operation.

TABLE 16-2: TAD vs. DEVICE OPERATING FREQUENCIES (EXTENDED VOLTAGE DEVICES (LC))

AD Clock Source (TAD)		Max FOSC (MHz)
Operation	ADCS1:ADCS0	
8TOSC	00	2.67
32TOSC	01	10.67
64TOSC	10	21.33
RC	11	—

Note: When the device frequency is greater than 1 MHz, the RC A/D conversion clock source is only recommended for SLEEP operation.

FIGURE 16-5: FLOW CHART OF A/D OPERATION



BSF **Bit Set f**

Syntax: [*label*] BSF f,b

Operands: $0 \le f \le 255$
$0 \le b \le 7$

Operation: $1 \rightarrow (f<b>)$

Status Affected: None

Encoding:

1000	0bbb	ffff	ffff

Description: Bit 'b' in register 'f' is set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: `BSF FLAG_REG, 7`

Before Instruction
FLAG_REG = 0x0A

After Instruction
FLAG_REG = 0x8A

BTFSC **Bit Test, skip if Clear**

Syntax: [*label*] BTFSC f,b

Operands: $0 \le f \le 255$
$0 \le b \le 7$

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

1001	1bbb	ffff	ffff

Description: If bit 'b' in register 'f' is 0, then the next instruction is skipped.

If bit 'b' is 0, then the next instruction fetched during the current instruction execution is discarded and a `NOP` is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

Example:
```
HERE    BTFSC   FLAG,1
FALSE   :
TRUE    :
```

Before Instruction
PC = address `(HERE)`

After Instruction
If FLAG<1> = 0;
PC = address `(TRUE)`
If FLAG<1> = 1;
PC = address `(FALSE)`

CPFSEQ — **Compare f with WREG, skip if f = WREG**

Syntax: [*label*] CPFSEQ f

Operands: $0 \le f \le 255$

Operation: (f) – (WREG), skip if (f) = (WREG) (unsigned comparison)

Status Affected: None

Encoding:

0011	0001	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of WREG by performing an unsigned subtraction.

If 'f' = WREG, then the fetched instruction is discarded and a NOP is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1 (2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

Example:

```
HERE    CPFSEQ REG
NEQUAL  :
EQUAL   :
```

Before Instruction
PC Address = HERE
WREG = ?
REG = ?

After Instruction
If REG = WREG;
PC = Address (EQUAL)
If REG ≠ WREG;
PC = Address (NEQUAL)

CPFSGT — **Compare f with WREG, skip if f > WREG**

Syntax: [*label*] CPFSGT f

Operands: $0 \le f \le 255$

Operation: (f) – (WREG), skip if (f) > (WREG) (unsigned comparison)

Status Affected: None

Encoding:

0011	0010	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of the WREG by performing an unsigned subtraction.

If the contents of 'f' are greater than the contents of WREG, then the fetched instruction is discarded and a NOP is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1 (2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

Example:

```
HERE      CPFSGT REG
NGREATER  :
GREATER   :
```

Before Instruction
PC = Address (HERE)
WREG = ?

After Instruction
If REG > WREG;
PC = Address (GREATER)
If REG £ WREG;
PC = Address (NGREATER)

DECF **Decrement f**

Syntax: [*label*] DECF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (f) – 1 → (dest)

Status Affected: OV, C, DC, Z

Encoding:

0000	011d	ffff	ffff

Description: Decrement register 'f'. If 'd' is 0, the result is stored in WREG. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `DECF CNT, 1`

Before Instruction
CNT = 0x01
Z = 0

After Instruction
CNT = 0x00
Z = 1

DECFSZ **Decrement f, skip if 0**

Syntax: [*label*] DECFSZ f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (f) – 1 → (dest);
skip if result = 0

Status Affected: None

Encoding:

0001	011d	ffff	ffff

Description: The contents of register 'f' are decremented. If 'd' is 0, the result is placed in WREG. If 'd' is 1, the result is placed back in register 'f'.

If the result is 0, the next instruction, which is already fetched is discarded and a `NOP` is executed instead, making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

Example:
```
HERE    DECFSZ  CNT, 1
        GOTO    HERE
NZERO
ZERO
```

Before Instruction
PC = Address `(HERE)`

After Instruction
CNT = CNT - 1
If CNT = 0;
PC = Address `(HERE)`
If CNT ≠ 0;
PC = Address `(NZERO)`

NOTES:

PIC17LC7XX-08 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
PIC17C7XX-16 (Commercial, Industrial, Extended) **PIC17C7XX-33** (Commercial, Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C for extended -40°C ≤ TA ≤ +85°C for industrial 0°C ≤ TA ≤ +70°C for commercial				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D010	IDD	**Supply Current (Note 2)**					
		PIC17LC7XX	—	3	6	mA	FOSC = 4 MHz **(Note 4)**
D010		PIC17C7XX	—	3	6	mA	FOSC = 4 MHz **(Note 4)**
D011		PIC17LC7XX	—	5	10	mA	FOSC = 8 MHz
D011		PIC17C7XX	—	5	10	mA	FOSC = 8 MHz
D012			—	9	18	mA	FOSC = 16 MHz
D014		PIC17LC7XX	—	85	150	µA	FOSC = 32 kHz, (EC osc configuration)
D015		PIC17C7XX	—	15	30	mA	FOSC = 33 MHz
D021	IPD	**Power-down Current (Note 3)**					
		PIC17LC7XX	—	<1	5	µA	VDD = 3.0V, WDT disabled
D021 (commercial, industrial)		PIC17C7XX	—	<1	20	µA	VDD = 5.5V, WDT disabled
D021A (extended)			—	2	20	µA	VDD = 5.5V, WDT disabled
		Module Differential Current					
D023	ΔIBOR	BOR circuitry	–	75	150	µA	VDD = 4.5V, BODEN enabled
D024	ΔIWDT	Watchdog Timer	–	10	35	µA	VDD = 5.5V
D026	ΔIAD	A/D converter	–	1	–	µA	VDD = 5.5V, A/D not converting

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD or VSS, T0CKI = VDD, MCLR = VDD; WDT disabled.

Current consumed from the oscillator and I/O's driving external capacitive or resistive loads needs to be considered.

For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD/(2 • R).

For capacitive loads, the current can be estimated (for an individual I/O pin) as (CL • VDD) • f

CL = Total capacitive load on the I/O pin; f = average frequency the I/O pin switches.

The capacitive currents are most significant when the device is configured for external execution (includes Extended Microcontroller mode).

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula IR = VDD/2REXT (mA) with REXT in kOhm.

5: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device (-16) will operate correctly to this trip point.

FIGURE 20-15: SPI SLAVE MODE TIMING (CKE = 0)

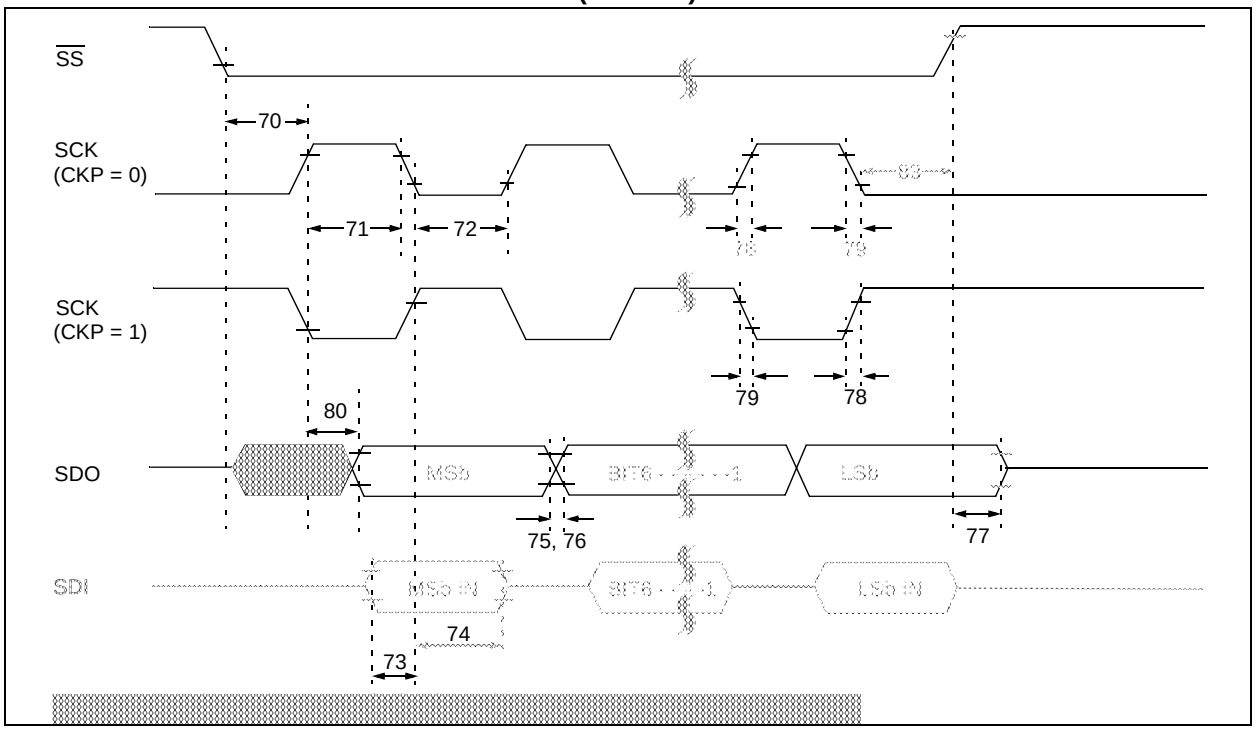


TABLE 20-10: SPI MODE REQUIREMENTS (SLAVE MODE TIMING, CKE = 0)

Param. No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SS}$↓ to SCK↓ or SCK↑ input		Tcy	—	—	ns	
71	TscH	SCK input high time (Slave mode)	Continuous	1.25TCY + 30	—	—	ns	
71A			Single Byte	40	—	—	ns	**(Note 1)**
72	TscL	SCK input low time (Slave mode)	Continuous	1.25TCY + 30	—	—	ns	
72A			Single Byte	40	—	—	ns	**(Note 1)**
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
73A	TB2B	Last clock edge of Byte1 to the 1st clock edge of Byte2		1.5TCY + 40	—	—	ns	**(Note 1)**
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
75	TdoR	SDO data output rise time		—	10	25	ns	
76	TdoF	SDO data output fall time		—	10	25	ns	
77	TssH2doZ	$\overline{SS}$↑ to SDO output hi-impedance		10	—	50	ns	
78	TscR	SCK output rise time (Master mode)		—	10	25	ns	
79	TscF	SCK output fall time (Master mode)		—	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge		—	—	50	ns	
83	TscH2ssH, TscL2ssH	$\overline{SS}$ ↑ after SCK edge		1.5TCY + 40	—	—	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: Specification 73A is only required if specifications 71A and 72A are used.

FIGURE 20-25: MEMORY INTERFACE READ TIMING

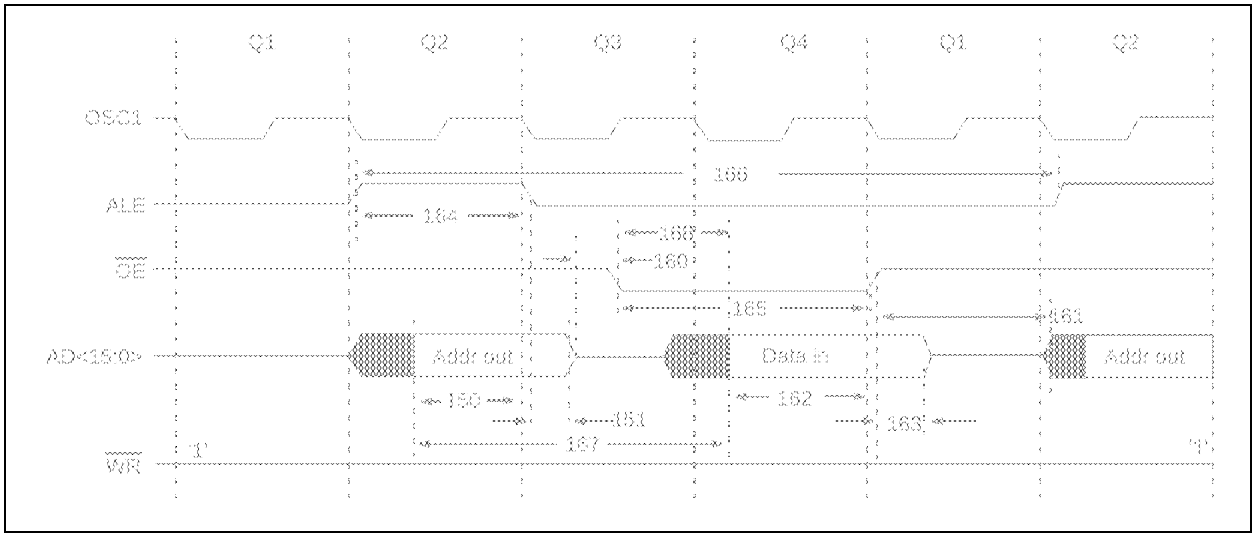


TABLE 20-21: MEMORY INTERFACE READ REQUIREMENTS

Param. No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD15:AD0 (address) valid to ALE↓ (address setup time)	PIC17**C**XXX	0.25TCY - 10	—	—	ns	
			PIC17**LC**XXX	0.25TCY - 10	—	—		
151	TalL2adI	ALE↓ to address out invalid (address hold time)	PIC17**C**XXX	5	—	—	ns	
			PIC17**LC**XXX	5	—	—		
160	TadZ2oeL	AD15:AD0 hi-impedance to $\overline{OE}$↓	PIC17**C**XXX	0	—	—	ns	
			PIC17**LC**XXX	0	—	—		
161	ToeH2adD	$\overline{OE}$↑ to AD15:AD0 driven	PIC17**C**XXX	0.25TCY - 15	—	—	ns	
			PIC17**LC**XXX	0.25TCY - 15	—	—		
162	TadV2oeH	Data in valid before $\overline{OE}$↑ (data setup time)	PIC17**C**XXX	35	—	—	ns	
			PIC17**LC**XXX	45	—	—		
163	ToeH2adI	$\overline{OE}$↑to data in invalid (data hold time)	PIC17**C**XXX	0	—	—	ns	
			PIC17**LC**XXX	0	—	—		
164	TalH	ALE pulse width	PIC17**C**XXX	—	0.25TCY	—	ns	
			PIC17**LC**XXX	—	0.25TCY	—		
165	ToeL	$\overline{OE}$ pulse width	PIC17**C**XXX	0.5TCY - 35	—	—	ns	
			PIC17**LC**XXX	0.5TCY - 35	—	—		
166	TalH2alH	ALE↑ to ALE↑(cycle time)	PIC17**C**XXX	—	TCY	—	ns	
			PIC17**LC**XXX	—	TCY	—		
167	Tacc	Address access time	PIC17**C**XXX	—	—	0.75TCY - 30	ns	
			PIC17**LC**XXX	—	—	0.75TCY - 45		
168	Toe	Output enable access time ($\overline{OE}$ low to data valid)	PIC17**C**XXX	—	—	0.5TCY - 45	ns	
			PIC17**LC**XXX	—	—	0.5TCY - 75		

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

FIGURE 21-19: TYPICAL, MINIMUM AND MAXIMUM VOH vs. IOH (VDD = 3V, -40°C TO +125°C)

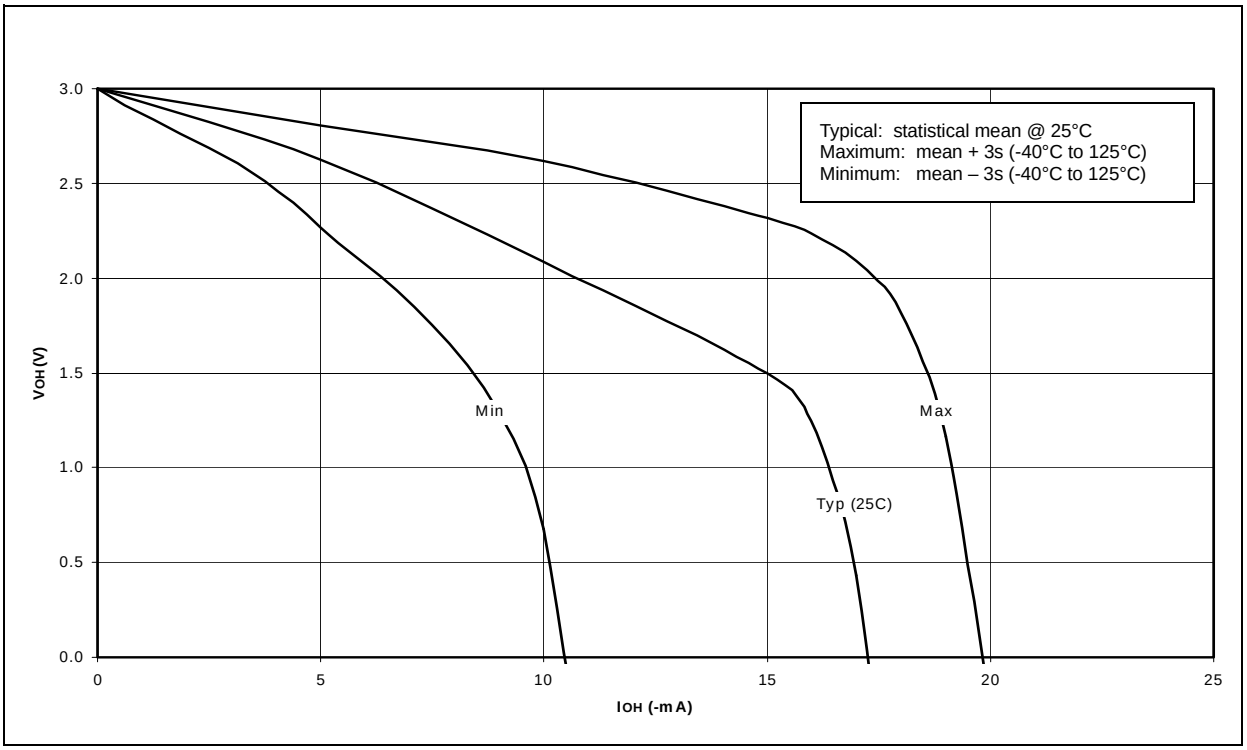
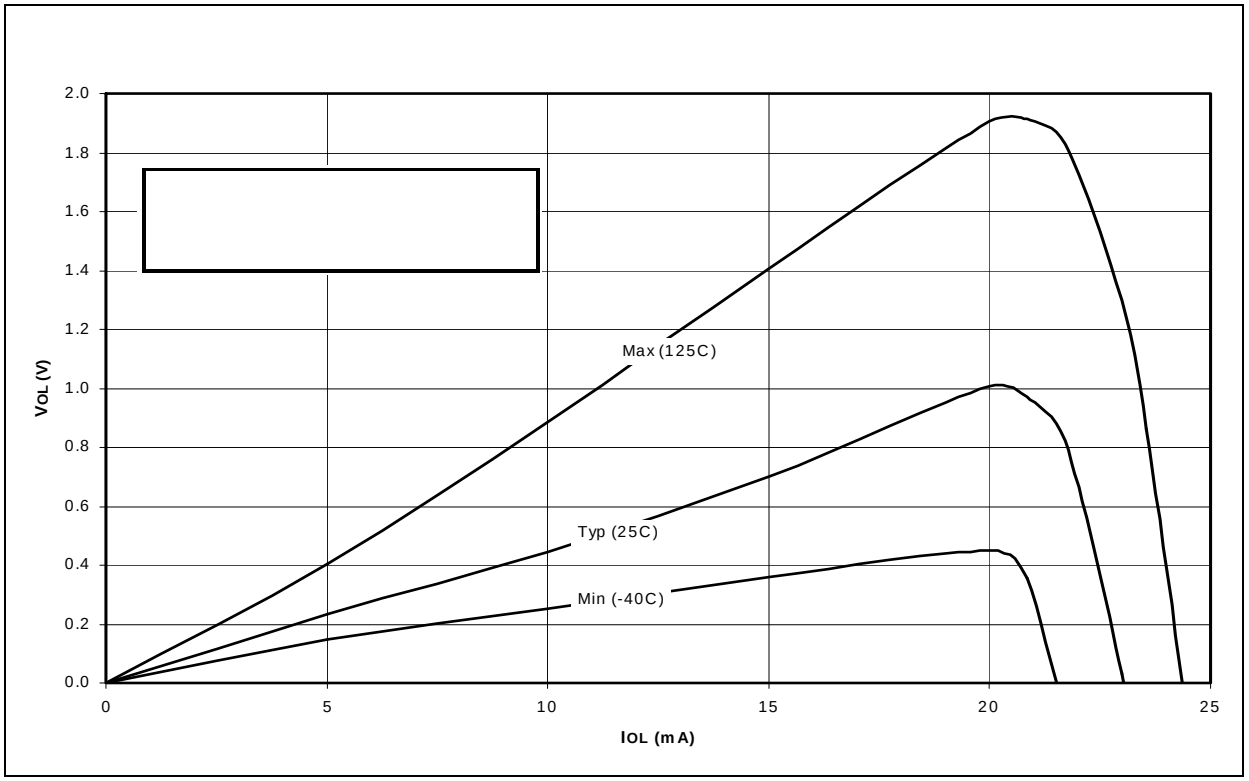


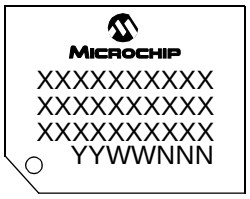
FIGURE 21-20: TYPICAL, MINIMUM AND MAXIMUM VOL vs. IOL (VDD = 3V, -40°C TO +125°C)



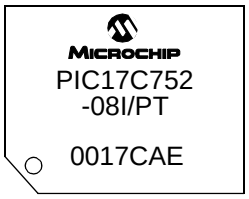
22.0 PACKAGING INFORMATION

22.1 Package Marking Information

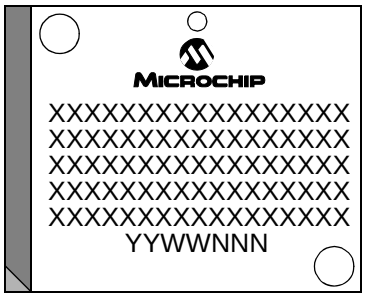
64-Lead TQFP



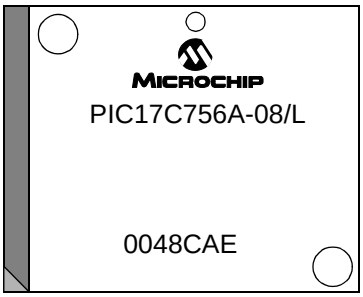
Example



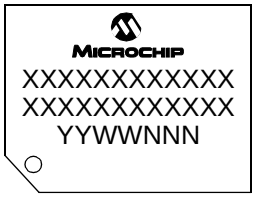
68-Lead PLCC



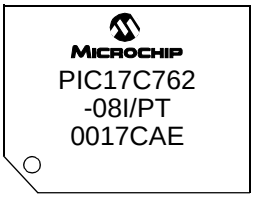
Example



80-Lead TQFP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.